# Get 9x Better Wheel Life When Grinding Hard Materials with Strasbaugh's 7AF-HMG

SAN LUIS OBISPO, Calif. July 6, 2016 – Strasbaugh (OTC: STRB), While the majority of SiC-based devices are built on 4" substrates, the transition to 6" production is now under way. Substrate suppliers and device makers are quickly finding that processing 6" SiC is extremely challenging, and the cost per wafer is significantly higher than the surface area increase would suggest due to the hardness of SiC.

To address this issue, Strasbaugh developed a hard-materials configuration of our new 7AF-II wafer grinder. This configuration, called the 7AF-HMG, combines hardware, software, and control-system improvements with grind wheels that are optimized specifically for SiC. This results in a wafer grinding solution that extends wheel life, increases tool uptime, boosts wafer output, and reduces the cost of ownership.  The grinder also improves process repeatability, reduces setup times, and maximizes wafer-to-wafer consistency.

For a typical backside thinning process, the savings compared with a non-optimized grinding system amounts to the following:

- Wheel life is nine times better
- 88 percent fewer wheel changes are required
- Production capacity increases by 16 percent
- Annual savings in wheel costs amount to nearly $1 million
- The return on investment is less than 12 months

"The 7AF-HMG is changing the way hard materials are being ground", stated Jerry Cutini Strasbaugh's CEO. "The performance gains and cost savings made possible with the 7AF-HMG are astounding and will go a long way to support the growth predicted for the SiC device industry."

Some of the key features of the 7AF-HMG wafer grinder include all-new modern controls, a Windows 7 based graphical user interface (GUI), real-time grind performance monitoring, endpoint control, and higher-powered spindle motors.

Additional benefits of the 7AF-HMG include: providing a wider process window ensuring that the system is not operating on the edge, which can cause longer-term problems such as wheel force-out and excessive wheel wear. It also makes setup quicker and easier.

Breakthroughs in the grinding process enable the wheels to self-dress, eliminating the need to dress the wheels between grinds. This further improves wheel life and increases productivity.

Contact Strasbaugh to arrange a demonstration and to see how much you can save on your SiC thinning process.

## About Strasbaugh

Strasbaugh manufactures CMP and grinding equipment for use in the production of nanotechnology for the Internet of Things (IoT), mobile computing platforms, LED lighting and a wide array of semiconductor devices. Since Strasbaugh was founded in 1948, the company has helped its customers realize their performance targets and has built a reputation as a world class manufacturer of innovative, reliable, high-yield surfacing solutions. Located in San Luis Obispo, CA, Strasbaugh offers new and certified refurbished systems for sale worldwide.

**Safe Harbor Statement Under the Private Securities Litigation Reform Act of 1995**

With the exception of historical information, the matters discussed in this press release, including without limitation, statements regarding the ability of the equipment to provide the benefits described are forward-looking statements involving a number of risks and uncertainties. Actual future results could differ. Factors that could cause or contribute to such differences include, but are not limited to, the ability of Strasbaugh to manufacture and deliver products pursuant to the terms of the purchase order, the projected future demand for Strasbaugh's products, changes in technology and governmental regulations and policies, competitive products and services, unforeseen technical issues and those factors contained in the "Risk Factors" Section of Strasbaugh's Form 10-K for the year ended December 31, 2009, and other Strasbaugh filings with the Securities and Exchange Commission.

Contacts
Strasbaugh
Sarah Okada
(805) 782-5416
sokada@strasbaugh.com